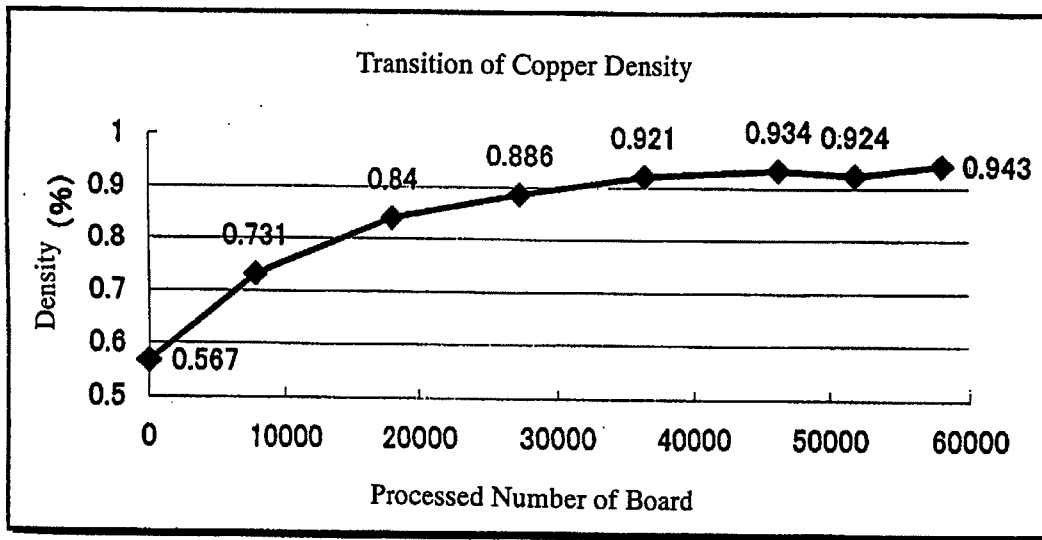
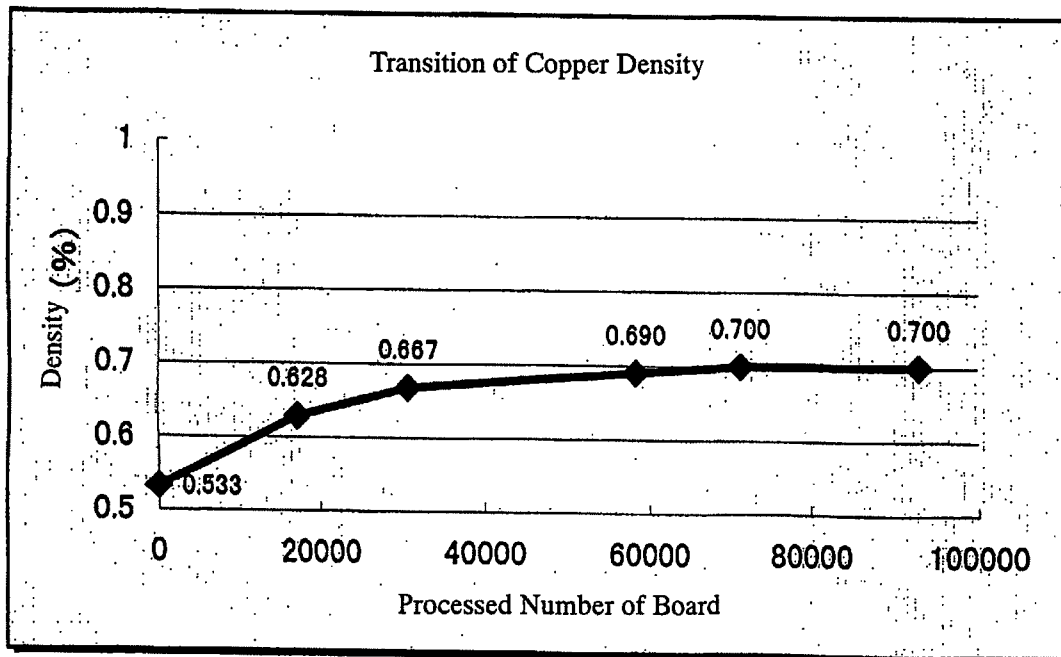


FIG 1



Transition of Copper density with continuously adding Sn-approx. 0.5% Cu-approx. 0.05% Ni solder

FIG2



Transition of Copper density with adding Sn-approx. 0.05% Ni alloy as a replenished solder